

| | Hits | Search Text | DBs |
|---|------|---|--|
| 1 | 4 | ((dielectric or substrate) near3 (Cu or copper or metal\$3 or conductive)) same ((photoresist or resist) near4 first) same (pattern\$4 or (expos\$4 near5 develop\$4) or mask) same (etch\$4 near5 (metal\$4 or conductive)) same (conductive near4 bump) same circuit\$5) and ((second near4 (photoresist or resist)) same (pattern\$4 or (expos\$4 near4 develop\$4) or mask) same (etch\$4 near5 (metal\$4 or conductive)) same dielectric) and ((second near4 (metal\$4 or conductive)) same dielectric same (conductive near3 bump) same interconnect\$4) | US-PGPUB; USPAT |
| 2 | 4 | (pluralit\$4 or multip\$3) near4 (conductive near4 bump) and interconnect\$4 and (first near4 (metal\$4 or conductive)) same (second near4 (conductive or metal\$4)) same ((first or initial) near5 (photoresist or resist)) same (pattern\$4 or (expos\$4 near6 develop\$4 or mask) same (conductive near3 bump)) and ((second near4 (photoresist or resist)) same expos\$4 same develop\$4) and ((third near4 (photoresist or resist)) same ((expos\$4 near6 develop\$5) or mask or pattern\$5) same (etch\$4 near5 (metal\$4 or conductive)) same (first or second) same dielectric) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB |
| 3 | 8 | ((("3767398") or ("3960561") or ("4209355") or ("4372804") or ("4983252") or ("5092032") or ("5200026") or ("5492233")).PN. | US-PGPUB; USPAT |

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|---|------|---|--|
| 4 | 4 | (((dielectric or substrate) near3 (Cu or copper or metal\$3 or conductive)) same ((photoresist or resist or photosensitive) near4 first) same (pattern\$4 or (expos\$4 near5 develop\$4) or mask) same (etch\$4 near5 (metal\$4 or conductive)) same ((conductive or metal\$4) near4 bump) same circuit\$5) and ((second near4 (photoresist or resist)) same (pattern\$4 or (expos\$4 near4 develop\$4) or mask) same (etch\$4 near5 (metal\$4 or conductive)) same dielectric) and ((second near4 (metal\$4 or conductive)) same dielectric same ((conductive or metal\$4) near3 bump) same interconnect\$4) | US-PGPUB; USPAT |
| 5 | 4 | (((dielectric or substrate) near3 (Cu or copper or metal\$3 or conductive)) same ((photoresist or resist or photosensitive) near4 first) same (pattern\$4 or (expos\$4 near5 develop\$4) or mask) same (etch\$4 near5 (metal\$4 or conductive)) same ((conductive or metal\$4) near4 bump) same circuit\$5) and ((second near4 (photoresist or resist)) same (pattern\$4 or (expos\$4 near4 develop\$4) or mask) same (etch\$4 near5 (metal\$4 or conductive)) same dielectric) and ((second near4 (metal\$4 or conductive)) same dielectric same ((conductive or metal\$4) near3 bump) same interconnect\$4) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB |
| 6 | 4 | ((pluralit\$4 or multip\$3) near4 ((conductive or metal\$3) near4 bump)) and interconnect\$4 and (first near4 (metal\$4 or conductive or Cu or copper)) same (second near4 (conductive or metal\$4 or aluminum or Al)) same ((first or initial) near5 (photoresist or resist or photosensitive)) same (pattern\$4 or (expos\$4 near6 develop\$4 or mask) same ((conductive or metal\$4) near3 bump)) and ((second near4 (photoresist or resist)) same expos\$4 same develop\$4) and ((third near4 (photoresist or resist)) same ((expos\$4 near6 develop\$5) or mask or pattern\$5) same (etch\$4 near5 (metal\$4 or conductive)) same (first or second) same | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB |

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|--|--|-------------|--|
| | | dielectric) | |
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|---|------|--|--|
| 7 | 4 | (((dielectric or substrate) near3 (Cu or copper or metal\$3 or conductive)) same ((photoresist or resist or photosensitive) near4 first) same (pattern\$4 or (expos\$4 near5 develop\$4) or mask) same (etch\$4 near5 (metal\$4 or conductive)) same ((conductive or metal\$4) near4 bump) same circuit\$5) and ((second near4 (photoresist or resist)) same (pattern\$4 or (expos\$4 near4 develop\$4) or mask) same (etch\$4 near5 (metal\$4 or conductive)) same dielectric) and ((second near4 (metal\$4 or conductive)) same dielectric same ((conductive or metal\$4) near3 bump) same interconnect\$4) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB |
| 8 | 4 | (((dielectric or substrate or wafer) near3 (Cu or copper or metal\$3 or conductive)) same ((photoresist or resist) near4 first) same (pattern\$4 or (expos\$4 near5 develop\$4) or mask) same (etch\$4 near5 (metal\$4 or conductive)) same (conductive near4 (land or bump)) same (line or circuit\$5 or (conduct\$5 near3 track))) and ((second near4 (photoresist or resist)) same (pattern\$4 or (expos\$4 near4 develop\$4) or mask) same (etch\$4 near5 (metal\$4 or conductive)) same dielectric) and ((second near4 (metal\$4 or conductive)) same dielectric same (conductive near3 (land or bump)) same interconnect\$4) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB |

| | Hits | Search Text | DBs |
|---|------|--|--|
| 9 | 4 | ((pluralit\$4 or multip\$3) near4 ((conductive or metal\$3) near4 (land or bump))) and interconnect\$4 and (first near4 (metal\$4 or conductive or Cu or copper)) same (second near4 (conductive or metal\$4 or aluminum or Al)) same ((first or initial) near5 (photoresist or resist or photosensitive)) same (pattern\$4 or (expos\$4 near6 develop\$4 or mask) same ((conductive or metal\$4) near3 (land or bump))) and ((second near4 (photoresist or resist)) same expos\$4 same develop\$4) and ((third near4 (photoresist or resist)) same ((expos\$4 near6 develop\$5) or mask or pattern\$5) same (etch\$4 near5 (metal\$4 or conductive)) same (first or second) same dielectric) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB |